



Product Change Notification

109013 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jcb.ijkk@intel.com

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Product Change Notification

Change Notification #: 109013 - 00
Change Title: MGM45RM, PCN 109013-00, Product Design, Mylar and Copper Foil Addition
Date of Publication: November 19, 2008

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 11, 2008
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Description of Change to the Customer:

Mylar and copper foil will be added to the bill of materials for each mobile board MGM45RM. The use of the Mylar and copper foil in the system will aid in reducing the temperature of the system touchpad area thus providing a better user experience. The Mylar is to be placed on the backside of the system keyboard and the copper foil is to be placed on the backside of the system C-plate. Instructions for installing the Mylar and copper foil will be included.

Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
LAMGM45RM	895540	E44405-403	E44405-404
BLKMG45RM	895544	E24789-403	E24789-404

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 19, 2008	00	Originally Published PCN